

Power MOS Field-Effect Transistors

N-Channel Enhancement-Mode Power Field-Effect Transistors

5.0A and 6.0A, 60V-100V

$r_{DS(on)} = 0.30 \Omega$ and 0.40Ω

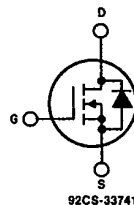
Features:

- SOA is power-dissipation limited
- Nanosecond switching speeds
- Linear transfer characteristics
- High input impedance
- Majority carrier device

The IRFF120, IRFF121, IRFF122 and IRFF123 are n-channel enhancement-mode silicon-gate power field-effect transistors designed for applications such as switching regulators, switching converters, motor drivers, relay drivers, and drivers for high-power bipolar switching transistors requiring high speed and low gate-drive power. These types can be operated directly from integrated circuits.

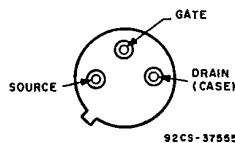
The IRFF-types are supplied in the JEDEC TO-205AF (LOW-PROFILE TO-39) metal package.

N-CHANNEL ENHANCEMENT MODE



TERMINAL DIAGRAM

TERMINAL DESIGNATION



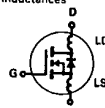
JEDEC TO-205AF

Absolute Maximum Ratings

Parameter	IRFF120	IRFF121	IRFF122	IRFF123	Units
V_{DS} Drain - Source Voltage ①	100	60	100	60	V
V_{DGR} Drain - Gate Voltage ($I_{GS} = 20 \text{ k}\Omega$) ①	100	60	100	60	V
$I_D @ T_C = 25^\circ\text{C}$ Continuous Drain Current	6.0	6.0	5.0	5.0	A
I_{DM} Pulsed Drain Current ③	24	24	20	20	A
V_{GS} Gate - Source Voltage	± 20				V
$P_D @ T_C = 25^\circ\text{C}$ Max. Power Dissipation	20 (See Fig. 14)				W
Linear Derating Factor	0.16 (See Fig. 14)				W/ $^\circ\text{C}$
I_{LM} Inductive Current, Clamped	(See Fig. 15 and 16) $L = 100\mu\text{H}$				A
	24	24	20	20	
T_J Operating Junction and	-55 to 150				$^\circ\text{C}$
T_{stg} Storage Temperature Range	-55 to 150				$^\circ\text{C}$
Lead Temperature	300 (0.063 in. (1.6mm) from case for 10s)				$^\circ\text{C}$

IRFF120, IRFF121, IRFF122, IRFF123

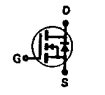
Electrical Characteristics @ $T_C = 25^\circ\text{C}$ (Unless Otherwise Specified)

Parameter		Type	Min	Typ	Max	Units	Test Conditions			
BV _{DSS}	Drain - Source Breakdown Voltage	IRFF120	100	-	-	V	$V_{GS} = 0\text{V}$ $I_D = 250\mu\text{A}$			
		IRFF122								
		IRFF121	60	-	-	V				
		IRFF123								
V _{GS(th)}	Gate Threshold Voltage	ALL	2.0	-	4.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu\text{A}$			
I _{GSS}	Gate-Source Leakage Forward	ALL	-	-	100	nA	$V_{GS} = 20\text{V}$			
I _{GSS}	Gate-Source Leakage Reverse	ALL	-	-	-100	nA	$V_{GS} = -20\text{V}$			
I _{DSS}	Zero Gate Voltage Drain Current	ALL	-	-	250	μA	$V_{DS} = \text{Max. Rating}$, $V_{GS} = 0\text{V}$			
			-	-	1000	μA	$V_{DS} = \text{Max. Rating} \times 0.8$, $V_{GS} = 0\text{V}$, $T_C = 125^\circ\text{C}$			
I _{D(on)}	On-State Drain Current ②	IRFF120	6.0	-	-	A	$V_{DS} \geq I_{D(on)} \times R_{DS(on) \text{ max.}}$, $V_{GS} = 10\text{V}$			
		IRFF121								
		IRFF122	5.0	-	-	A				
R _{DS(on)}	Static Drain-Source On-State Resistance ②	IRFF120	-	0.25	0.30	Ω	$V_{GS} = 10\text{V}$, $I_D = 3.0\text{A}$			
		IRFF121								
		IRFF122	-	0.30	0.40	Ω				
g _f	Forward Transconductance ②	ALL	1.5	2.9	-	S/(V)	$V_{DS} \geq I_{D(on)} \times R_{DS(on) \text{ max.}}$, $I_D = 3.0\text{A}$			
C _{iss}	Input Capacitance	ALL	-	450	600	pF	$V_{GS} = 0\text{V}$, $V_{DS} = 25\text{V}$, $f = 1.0\text{MHz}$			
C _{oss}	Output Capacitance	ALL	-	200	400	pF	See Fig. 10			
C _{rss}	Reverse Transfer Capacitance	ALL	-	50	100	pF				
t _{d(on)}	Turn-On Delay Time	ALL	-	20	40	ns	$V_{DD} = 0.5\text{BV}_{DSS}$, $I_D = 3.0\text{A}$, $Z_\theta = 50\Omega$ See Fig. 17 (MOSFET switching times are essentially independent of operating temperature.)			
t _r	Rise Time	ALL	-	37	70	ns				
t _{d(off)}	Turn-Off Delay Time	ALL	-	50	100	ns				
t _f	Fall Time	ALL	-	35	70	ns				
Q _g	Total Gate Charge (Gate-Source Plus Gate-Drain)	ALL	-	10	15	nC	$V_{GS} = 10\text{V}$, $I_D = 10\text{A}$, $V_{DS} = 0.8\text{Max. Rating}$ See Fig. 18 for test circuit. (Gate charge is essentially independent of operating temperature.)			
		Q _{gs}	Gate Source Charge	ALL	-	6.0			-	nC
		Q _{gd}	Gate Drain ("Miller") Charge	ALL	-	4.0			-	nC
L _D	Internal Drain Inductance	ALL	-	5.0	-	nH	Measured from the drain lead, 5 mm (0.2 in.) from header to center of die	Modified MOSFET symbol showing the internal device inductances 		
L _S	Internal Source Inductance	ALL	-	15	-	nH	Measured from the source lead, 5 mm (0.2 in.) from header to source bonding pad			

Thermal Resistance

R _{thJC}	Junction-to Case	ALL	-	-	6.25	$^\circ\text{C}/\text{W}$	
R _{thJA}	Junction-to Ambient	ALL	-	-	175	$^\circ\text{C}/\text{W}$	Free Air Operation

Source-Drain Diode Ratings and Characteristics

I _S	Continuous Source Current (Body Diode)	IRFF120	-	-	6.0	A	Modified MOSFET symbol showing the integral reverse P-N junction rectifier 
		IRFF121					
		IRFF122	-	-	5.0	A	
I _{SM}	Pulse Source Current (Body Diode) ③	IRFF120	-	-	24	A	
		IRFF121					
		IRFF122	-	-	20	A	
V _{SD}	Diode Forward Voltage ②	IRFF120	-	-	2.5	V	$T_C = 25^\circ\text{C}$, $I_S = 6.0\text{A}$, $V_{GS} = 0\text{V}$
		IRFF121					
		IRFF122	-	-	2.3	V	
t _{rr}	Reverse Recovery Time	ALL	-	230	-	ns	$T_J = 150^\circ\text{C}$, $I_F = 6.0\text{A}$, $dI_F/dt = 100\text{A}/\mu\text{s}$
Q _{RR}	Reverse Recovered Charge	ALL	-	1.2	-	μC	$T_J = 150^\circ\text{C}$, $I_F = 6.0\text{A}$, $dI_F/dt = 100\text{A}/\mu\text{s}$
t _{on}	Forward Turn on Time	ALL	Intrinsic turn on time is negligible. Turn on speed is substantially controlled by L _S + L _D				

① $T_J = 25^\circ\text{C}$ to 150°C .

② Pulse Test: Pulse width $< 300\mu\text{s}$, Duty Cycle $< 2\%$

③ Repetitive Rating: Pulse width limited by max. junction temperature.

See Transient Thermal Impedance Curve (Fig. 5).

IRFF120, IRFF121, IRFF122, IRFF123

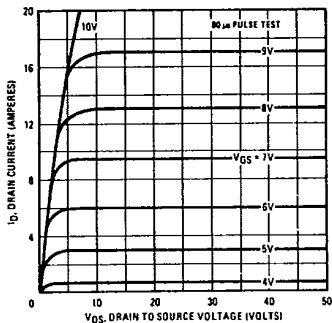


Fig. 1 — Typical Output Characteristics

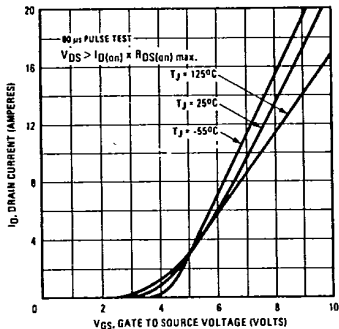


Fig. 2 — Typical Transfer Characteristics

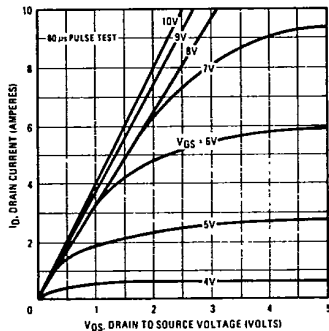


Fig. 3 — Typical Saturation Characteristics

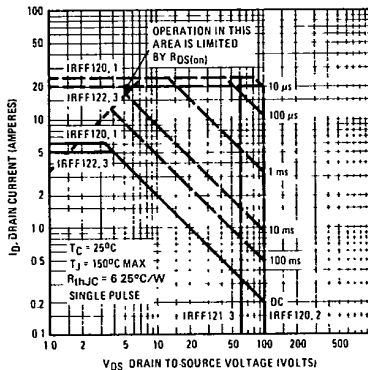


Fig. 4 — Maximum Safe Operating Area

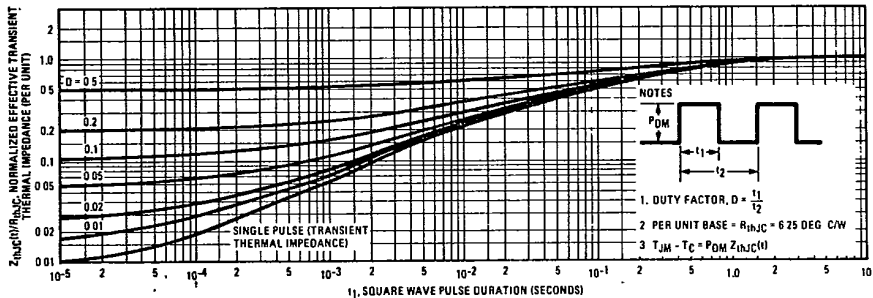


Fig. 5 — Maximum Effective Transient Thermal Impedance, Junction-to-Case Vs. Pulse Duration

IRFF120, IRFF121, IRFF122, IRFF123

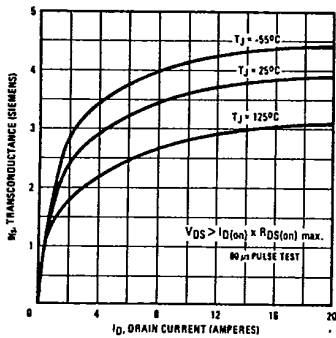


Fig. 6 – Typical Transconductance Vs. Drain Current

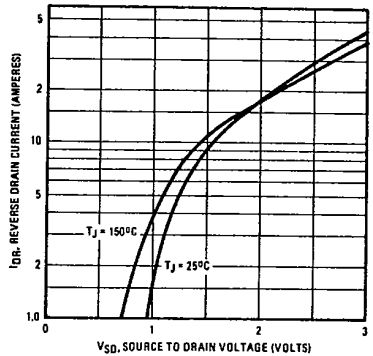


Fig. 7 – Typical Source-Drain Diode Forward Voltage

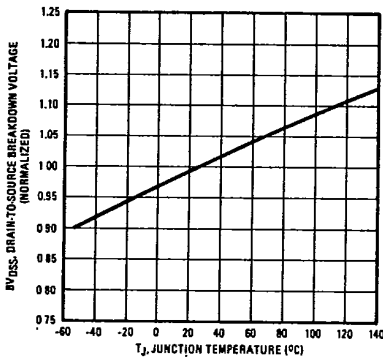


Fig. 8 – Breakdown Voltage Vs. Temperature

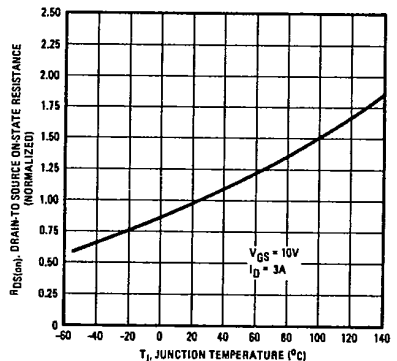


Fig. 9 – Normalized On-Resistance Vs. Temperature

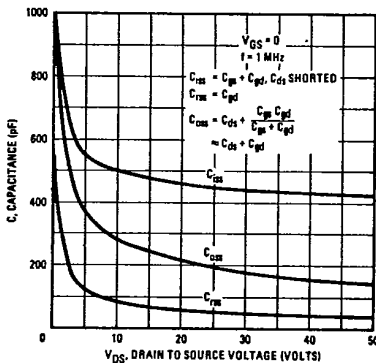


Fig. 10 – Typical Capacitance Vs. Drain-to-Source Voltage

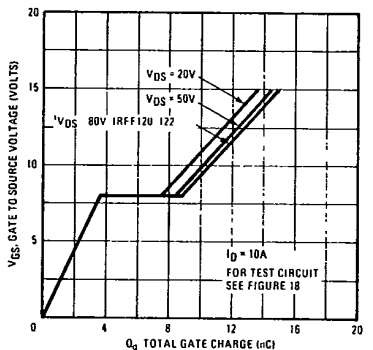


Fig. 11 – Typical Gate Charge Vs. Gate-to-Source Voltage

IRFF120, IRFF121, IRFF122, IRFF123

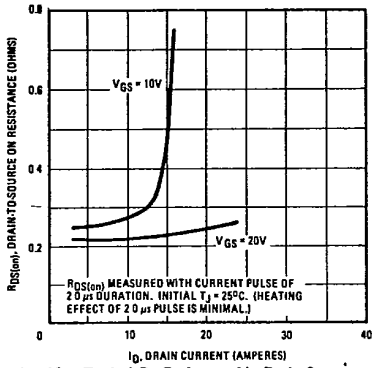


Fig. 12 – Typical On-Resistance Vs. Drain Current

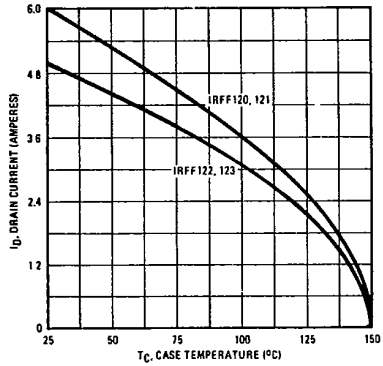


Fig. 13 – Maximum Drain Current Vs. Case Temperature

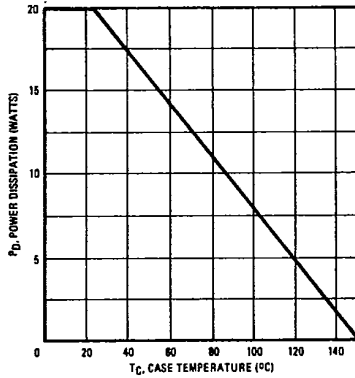


Fig. 14 – Power Vs. Temperature Derating Curve

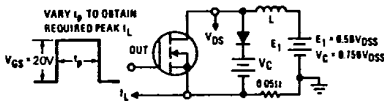


Fig. 15 – Clamped Inductive Test Circuit

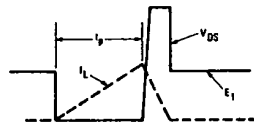


Fig. 16 – Clamped Inductive Waveforms

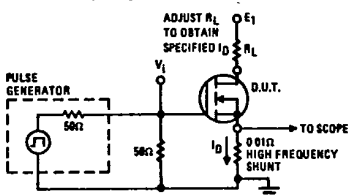


Fig. 17 – Switching Time Test Circuit

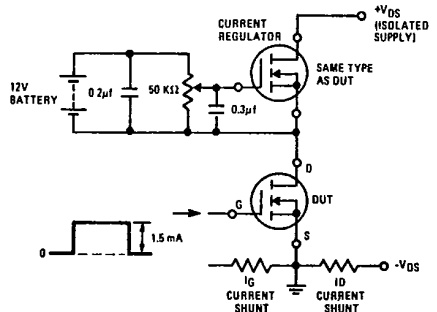


Fig. 18 – Gate Charge Test Circuit